

Injection de fautes : attaques physiques, protections logicielles et mécanismes d'évaluation de la robustesse



EM injections on cryptographic implementations on SoC

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EM injections on cryptographic implementations on SoC

1. Introduction
2. Methodology
3. Experimentations
4. Analysis

1. INTRODUCTION

- Context
- SoC characteristics

1. Introduction

- ✧ Fault injection on digital security devices is a prolific subject
(2006) *The Sorcerer's Apprentice Guide to Fault Attacks* [H. Bar-EI *et al.*]
 - Focused on microcontrollers and smartcard...
- ✧ Today, complex **S**ystem **o**n **C**hip (SoC) are implied into several security task:
 - Relative to ID of the users (credentials)
 - Relative to safety of the users (automotive)



What threats FAs represent on such devices?



1. Introduction

SoC features:

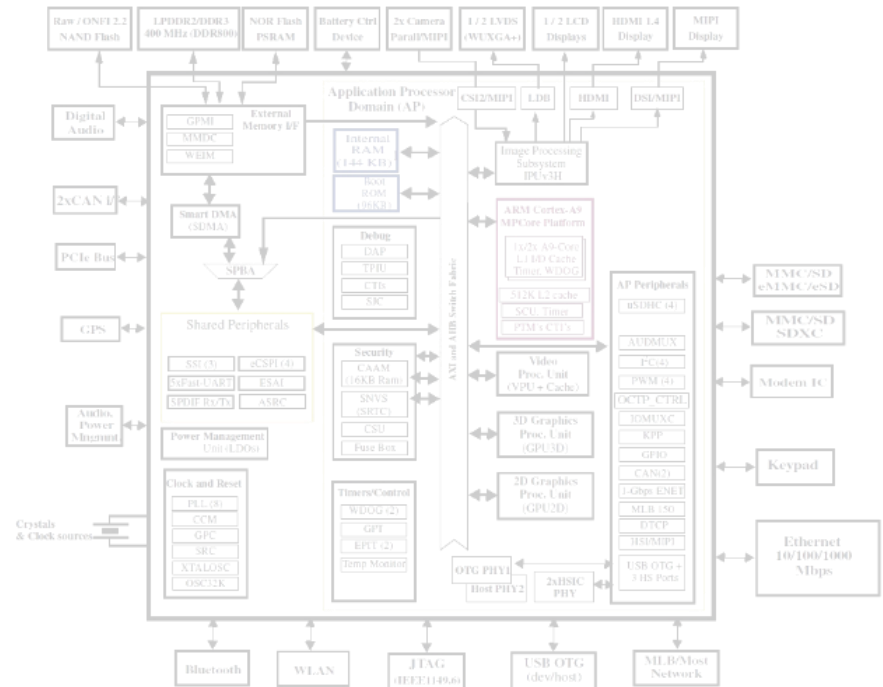
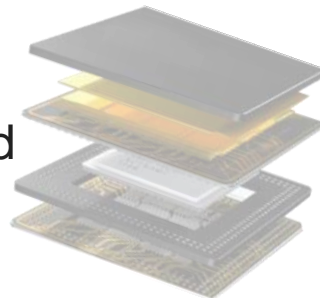


✦ Rich OS based on complex architecture

- Powerful Multicores
- Several clock trees
- Several power supplies
- A lot of peripherals
- Cryptographic accelerator
- Secure internal memories
- etc...

✦ Context

- SoC are soldered
- Package
- Size
- etc...



How efficient are FAs on these devices ?



2. TARGET AND METHODOLOGY

- Which physical quantity is the most appropriated?
- DUT description
- Our methodology

2. Target and methodology

Which physical quantity is appropriate ?

- ✦ To make a Fault Attack on a process:
 - Analysis (to localize the time and the area)
 - Inject a disturbance on a suitable physical quantity
- ✦ Several technologies to inject a fault: Glitch, Laser, EM...
- ✦ Electromagnetic field (EM field)
Analysis (**EM Side-channel**) and Disturbance (**EM Fault Injection**)
 - Through the package
 - Without unsoldering components
 - Localized disturbances



Electromagnetic field is the most convenient physical quantity to observe and disturb a SoC without damaging it.

2. Target and methodology

The targeted device:

- ✦ SoC : CMOS 40nm, Cortex-A9 (1GHz) , 32-bits, DDR3 memory, Cache L1 & L2...
- ✦ 2 possible cryptographic implementations:
CPU and/or crypto accelerator

The test consists in studying the effect of EM injection on an AES encryption executed by the CPU and by the crypto-accelerator.

1. AES on CPU:

- **Straightforward code without counter measures**

2. AES on crypto accelerator:

- Security Module : dedicated clock tree, DMA, interrupts, crypto-accelerators,....

2. Target and methodology

Principle of our methodology:

- 1. EM side-Channel Analysis** to localize in space and time the targeted device (module computing the AES)
 - EM side-channel mapping of the SoC by stimulating the AES with suitable data
 - Emissions analysis
 - Timing localization for the FA
- 2. EM Injection** to check if an exploitable fault is possible
 - Inject a pulse during the round 9 of the AES (DFA)
 - Injection mapping to cover the entire SoC surface
- 3. Results analysis**

3. AES ON CPU : EXPERIMENTATION

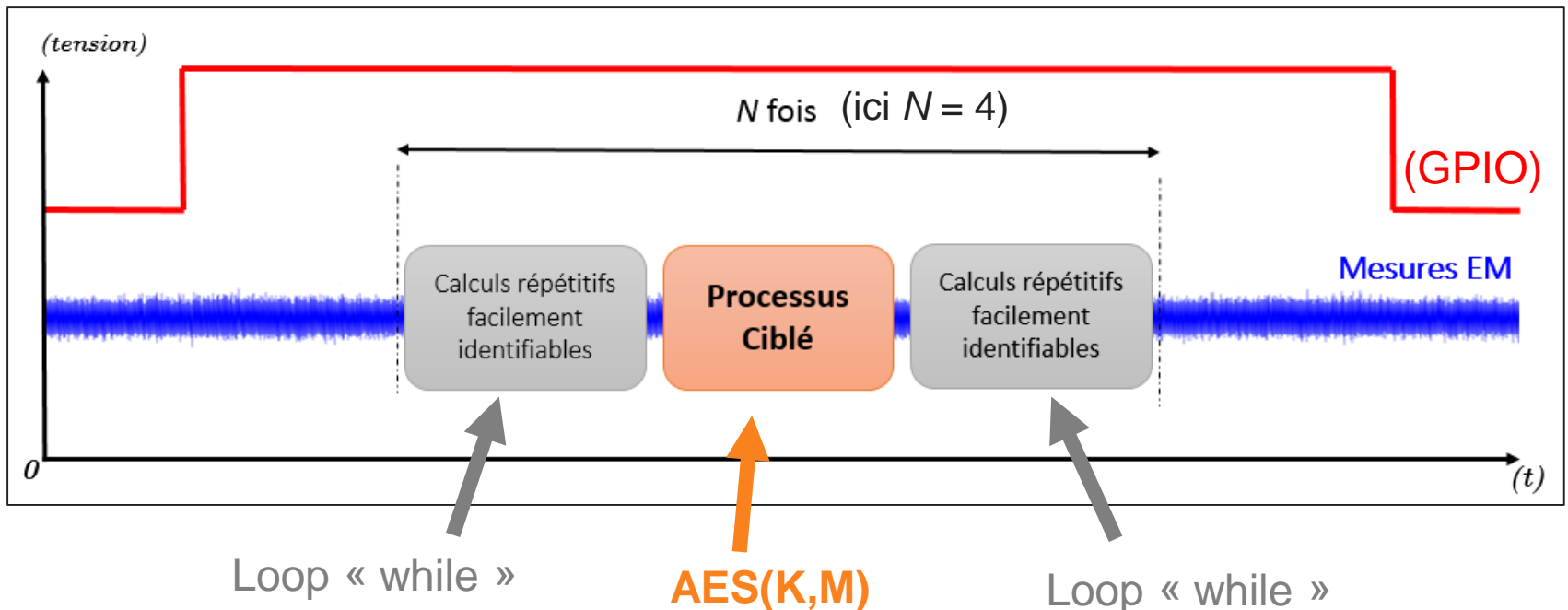
- 3.1 EM side-channel analysis
- 3.2 EM fault injection
- 3.3 Analysis

3.1. Side-channel analysis

✦ Setup: AES computed by CPU.

AES encryption:

K = 3B E3 22 66 2F 3B E8 41 50 2E 79 41 46 05 25 49
M = RR RR RR RR RR RR RR RR RR RR RR RR RR RR RR RR



3.1. Side-channel analysis

✧ Setup:

Control PC

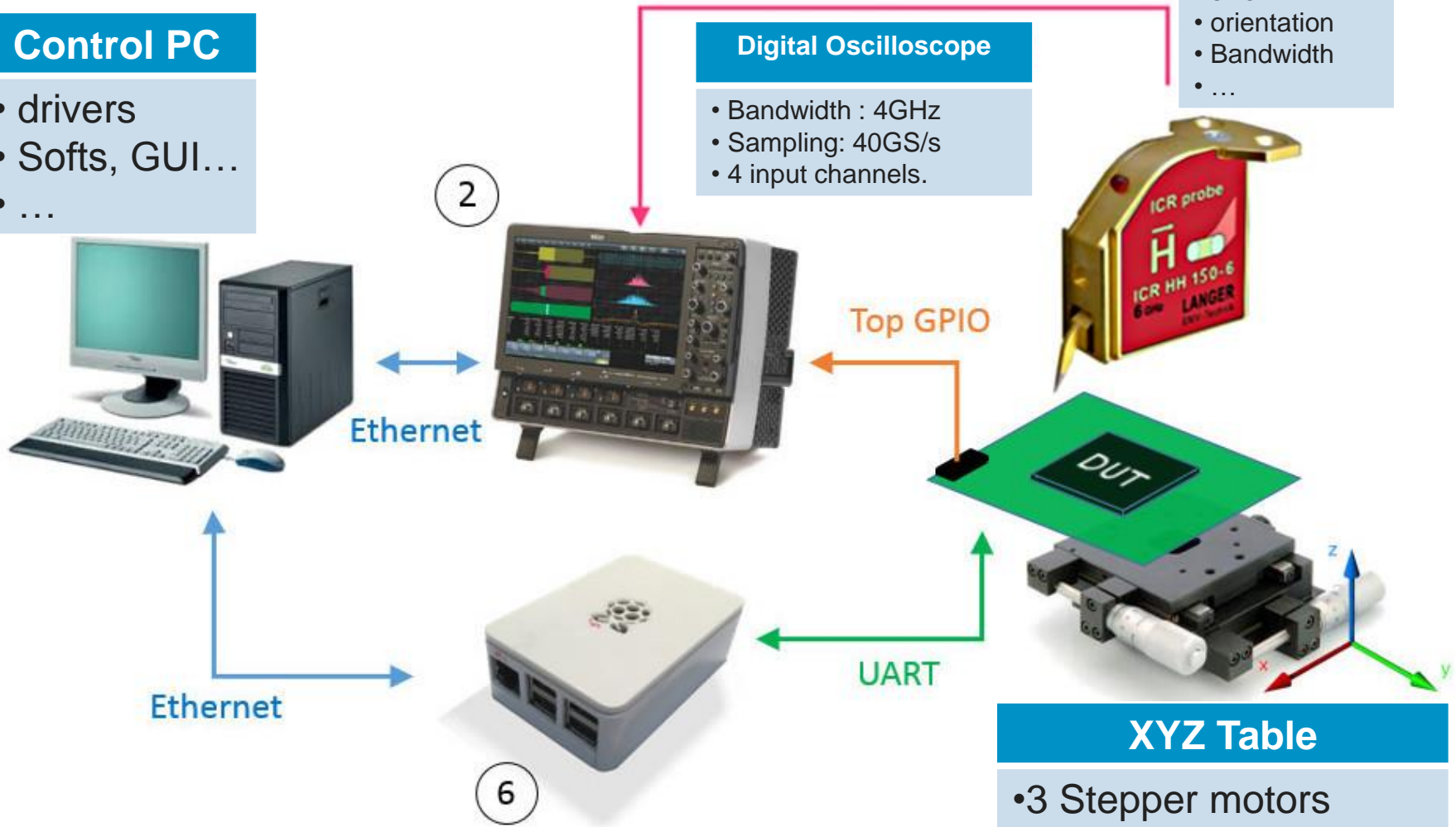
- drivers
- Softs, GUI...
- ...

Digital Oscilloscope

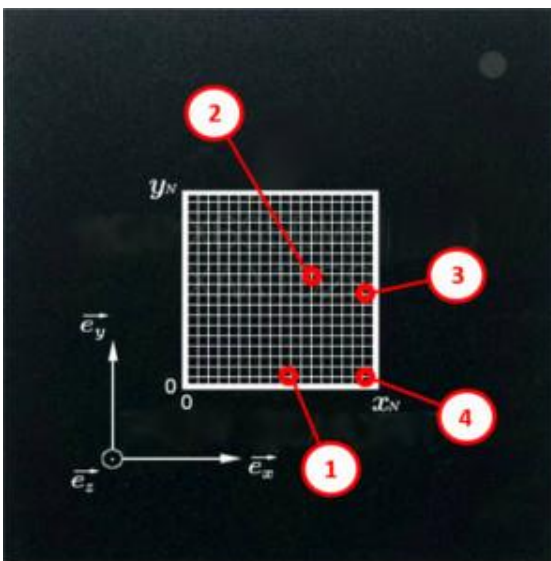
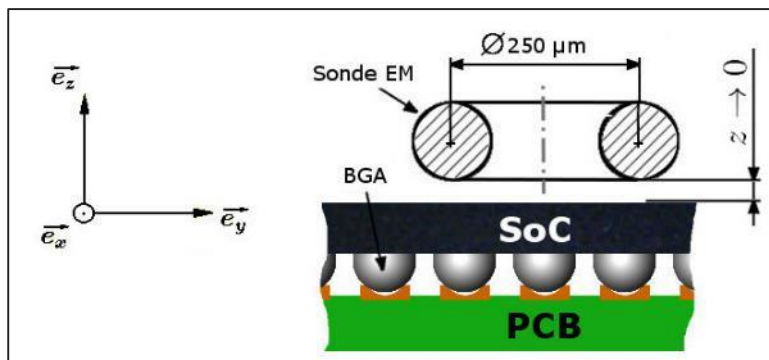
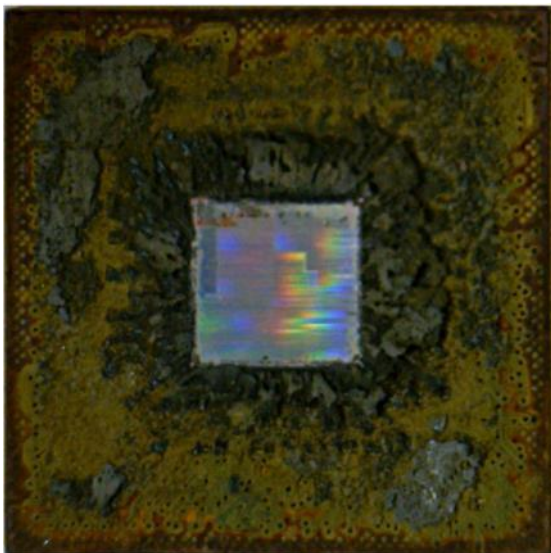
- Bandwidth : 4GHz
- Sampling: 40GS/s
- 4 input channels.

EM μ -probes

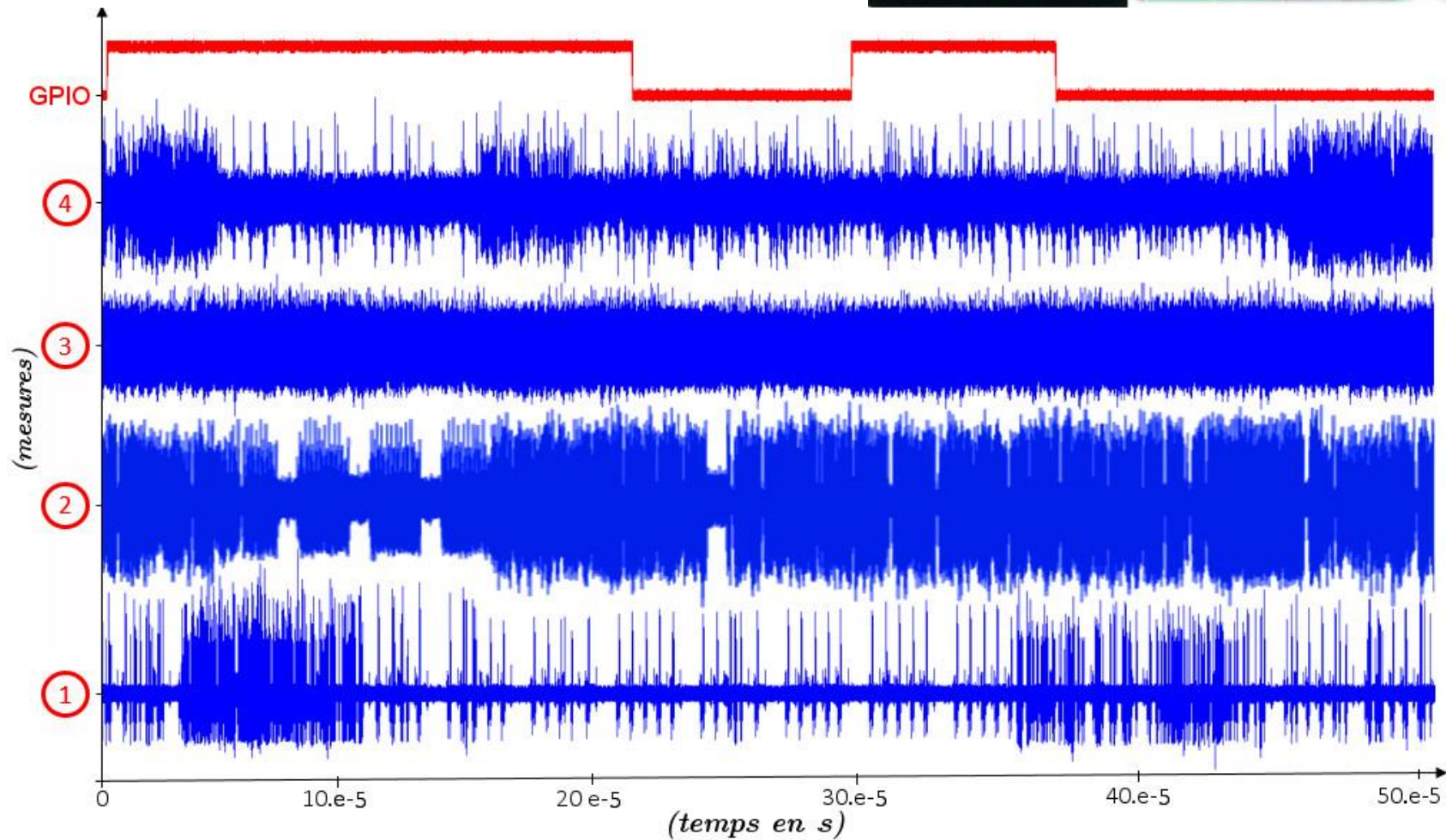
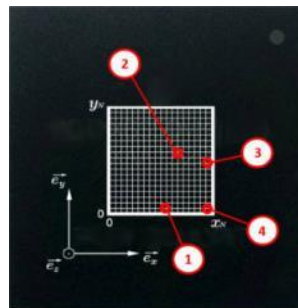
- size
- orientation
- Bandwidth
- ...



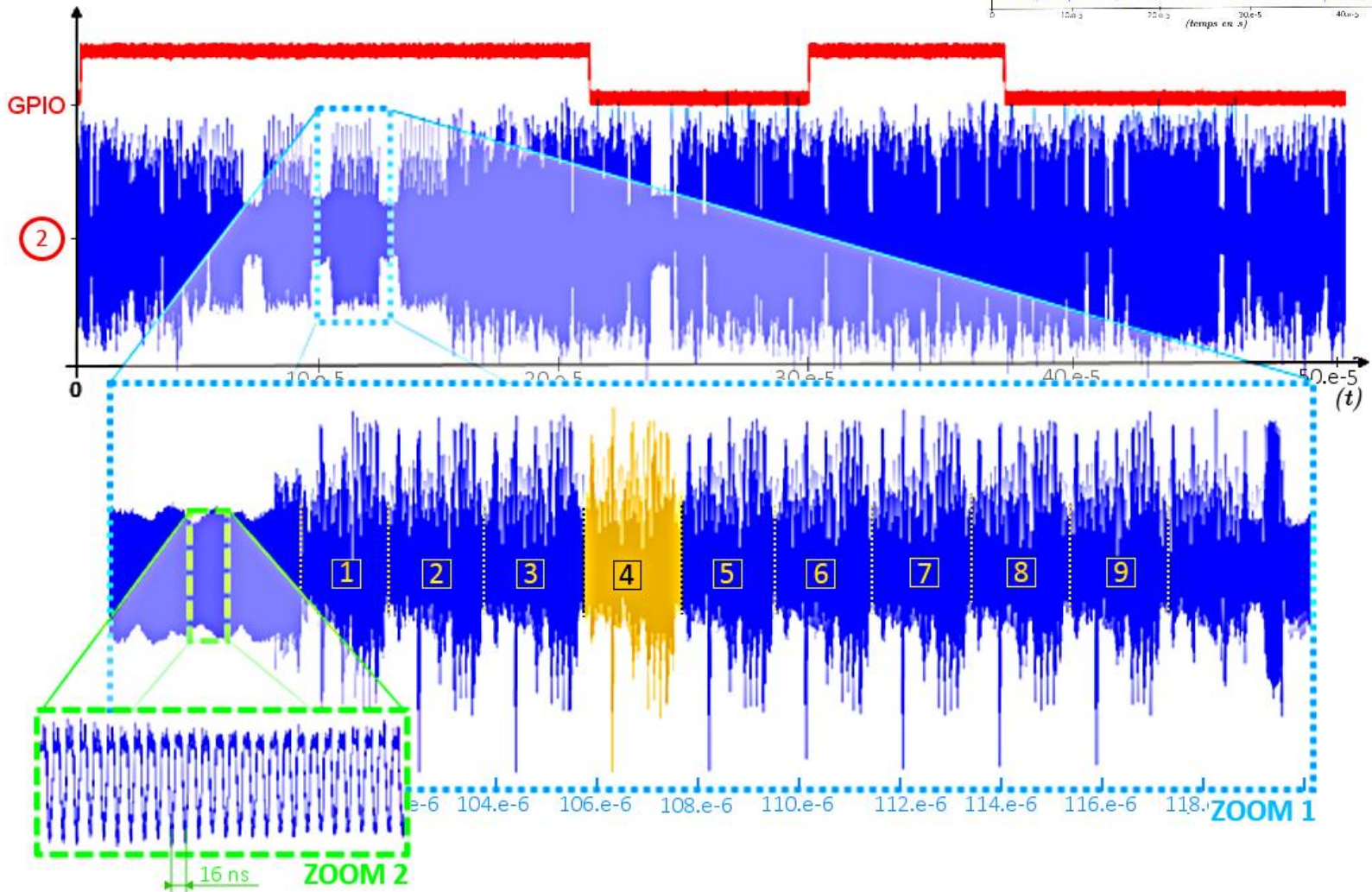
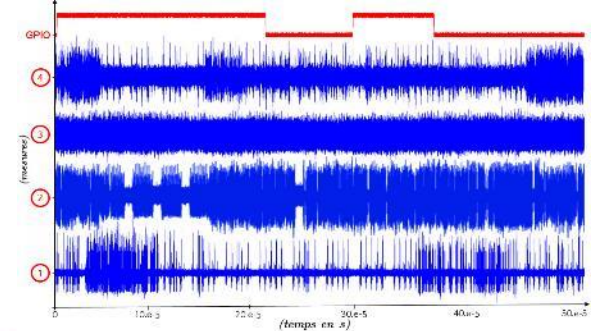
3.1. Side-channel analysis



3.1. Side-channel analysis



3.1. Side-channel analysis



3. AES ON CPU : EXPERIMENTATION

- 3.1 EM side-channel analysis
- 3.2 EM fault injection
- 3.3 Analysis

3.2. Fault injection

✧ DFA

→ change 1 Byte value of the « state »
[ShiftRow-9] **X** [Mixcolumn-9]

AES encryption:

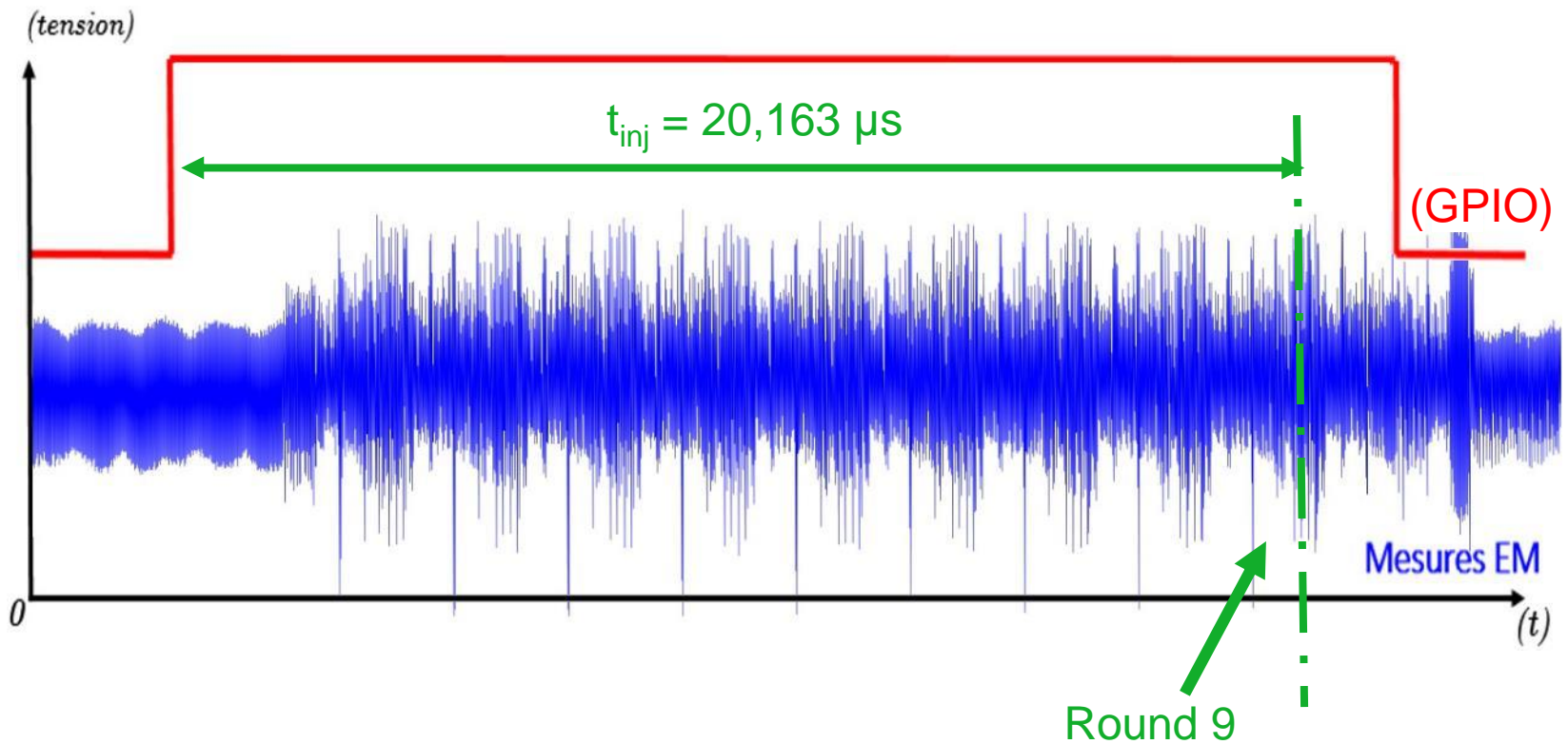
K = 3B E3 22 66 2F 3B E8 41 50 2E 79 41 46 05 25 49
M = 11 11 11 11 11 11 11 11 11 11 11 11 11 11 11 11
C = AF E6 93 58 DE C5 71 93 28 2C 2F B6 B8 AB 62 16

Exploitable Faults: (≈ 50 different faults requested)

	$C_{0,0}$	$C_{1,0}$	$C_{2,0}$	$C_{3,0}$	$C_{0,1}$	$C_{1,1}$	$C_{2,1}$	$C_{3,1}$	$C_{0,2}$	$C_{1,2}$	$C_{2,2}$	$C_{3,2}$	$C_{0,3}$	$C_{1,3}$	$C_{2,3}$	$C_{3,3}$
F_1	XX	E6	93	58	DE	C5	71	XX	28	2C	XX	B6	B8	XX	62	16
F_2	AF	XX	93	58	XX	C5	71	93	28	2C	2F	XX	B8	AB	XX	16
F_3	AF	E6	XX	58	DE	XX	71	93	XX	2C	2F	B6	B8	AB	62	XX
F_4	AF	E6	93	XX	DE	C5	XX	93	28	XX	2F	B6	XX	AB	62	16

3.2. Fault injection

✧ From the side-channel analysis:



3.2. Fault injection

✧ Setup:

Control PC

- drivers
- Softs, GUI...
- ...

Pulse generator

- Amplitude: 0 – 400V
- Duration: 6 – 100 ns.

EM injectors

- shape
- size
- ...

1



Top

5



Digital Oscilloscope

- Bandwidth : 4GHz
- Sampling: 40GS/s
- 4 input channels.

2



Top GPIO

8



UART

Ethernet

7



XYZ Table

- 3 Stepper motors



3.2. Fault injection

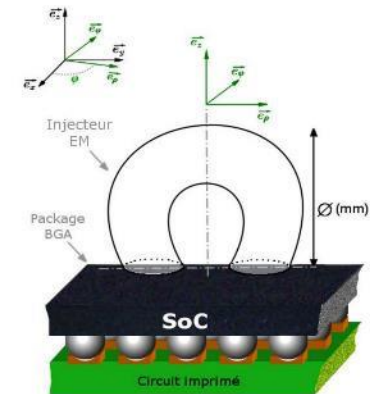
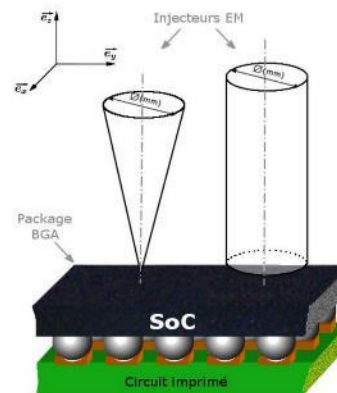
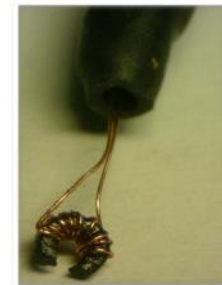
✧ Several EM injectors with different parameters

- Size
- number of spire
- Symmetry

Experimental setup build on trial and error to:

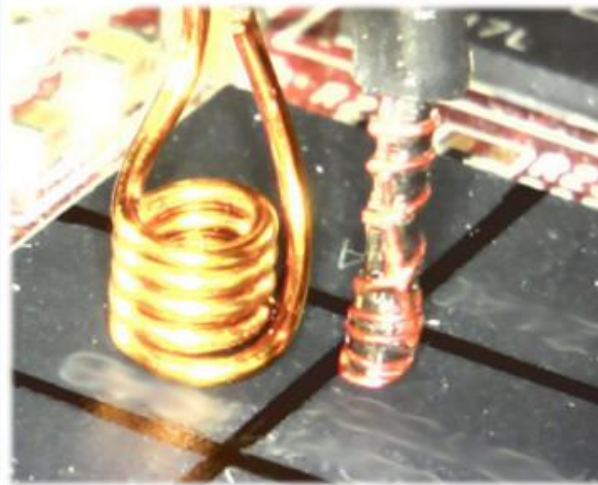
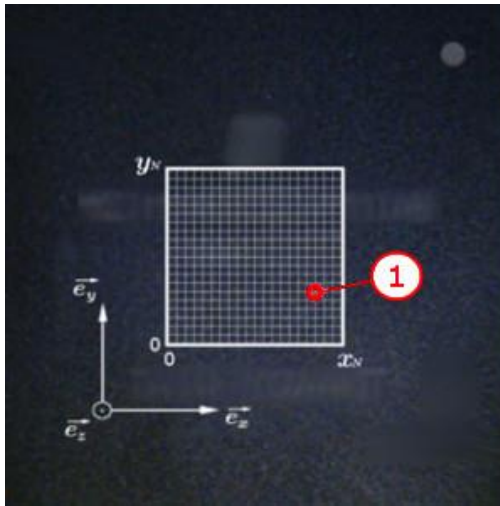
- Find the most suitable EM injector
- Find a place where to inject faults.

1. EM pulse +400V, 6ns
2. Localize the <mute>
3. Adjust the pulse

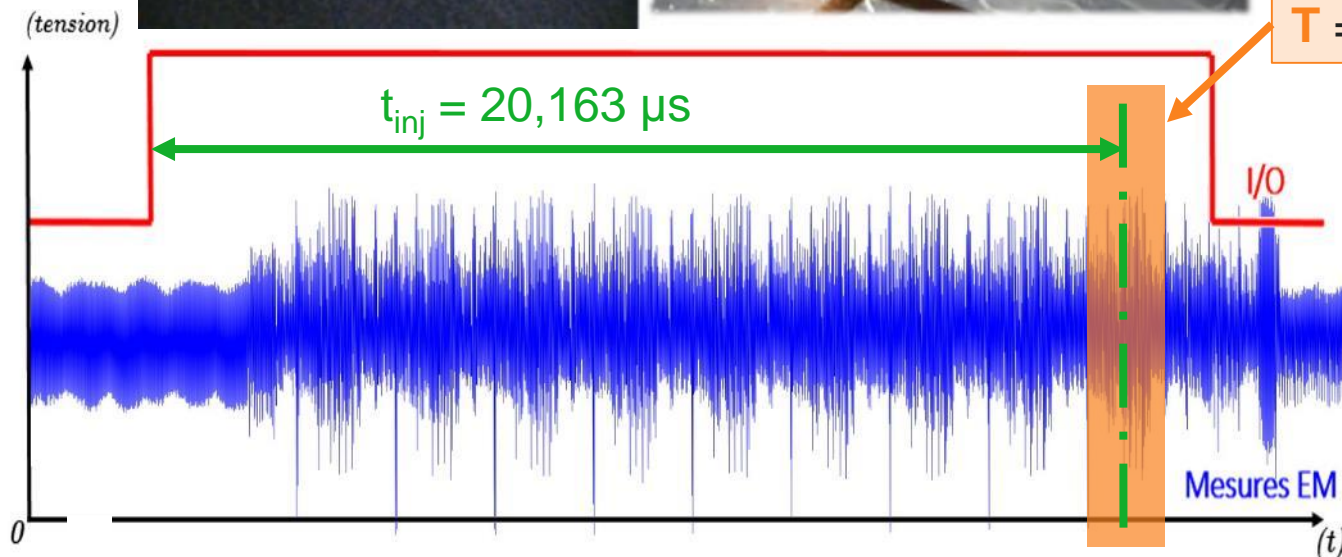


3.2. Fault injection

✧ Most significant results obtained on this point.



$\Delta A_{inj} = +290V$ (10% mutes)
 $\Delta T_{inj} = 6ns$
 $T_{inj} = 20,163 \mu s$
Time window: **T**
Step: 1ns
Times : 10



T = $[t_{inj}-500ns; t_{inj}+500ns]$

3. AES ON CPU : EXPERIMENTATION

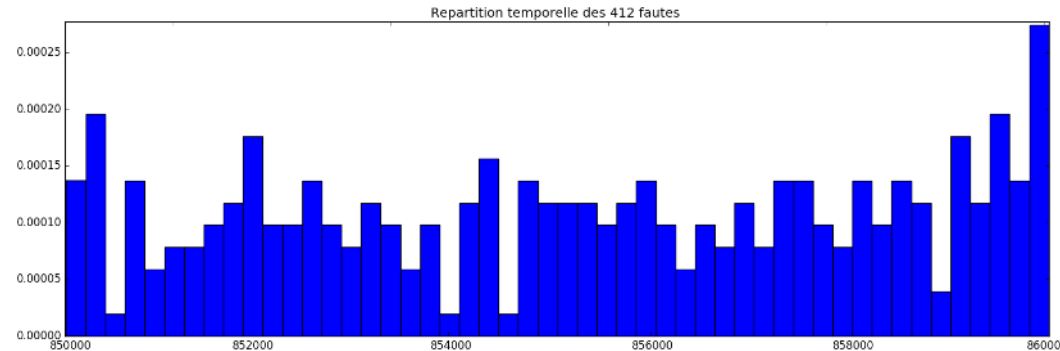
- 3.1 EM side-channel analysis
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3.2. Fault injection

10 000 tries done in 18h
 1207 mutes (12%)
 412 faults (4%)
 45 exploitable faults

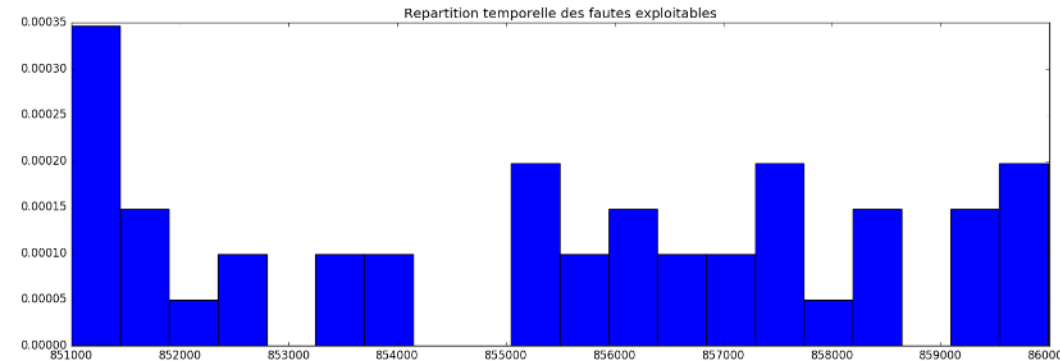
temporal distribution

All faults



n° identifiant	Valeur du <faute>	(occurrences)	Type
(Chiffré Ref.)	AF E6 93 58 DE C5 71 93 28 2C 2F B6 B8 AB 62 16		
0012 72 B7 70 8B	(1 times)	F ₃
0014 1E 73 75 A3	(1 times)	F ₄
0027	CE 78 78 9E	(3 times)	F ₁
0044 F1 F1 29 68	(3 times)	F ₄
0067 14 D1 49 A7	(2 times)	F ₄
0075	02 88 A6 CO	(6 times)	F ₁
0099	06 26 B6 8F	(2 times)	F ₁
0161 1C DB 6A 2A	(1 times)	F ₄
0163 13 31 6D 6F	(5 times)	F ₄
0171	16 66 EE CA	(1 times)	F ₁
0181 90 AF 79 2B	(5 times)	F ₄
0198	.. 07 E9 EE 83 ..	(1 times)	F ₂
0208	07 AC AC 21	(1 times)	F ₁
0220	.. C3 AD 3C EF ..	(1 times)	F ₂
0223	25 20 6E 1C	(1 times)	F ₁
0224	1A E4 A6 0D	(1 times)	F ₁
0273	.. C3 EB 7C 99	(1 times)	F ₂
0297	48 2C 2E C3	(2 times)	F ₁
0301	.. C3 E9 3C 40 ..	(1 times)	F ₂
0308	.. C6 E8 4E A3 ..	(1 times)	F ₂
0316 5E D1 7A C3	(5 times)	F ₃

Exploitable faults



3.2. Fault injection : Conclusion

- ✧ No difficulties to disturb the AES computed by CPU
- ✧ We obtained the faults we expected
- ✧ In only 10 000 pulse injections → 45 exploitable faults
- ✧ Possible improvements : pattern matching to trig the pulse injection.

4. Analysis / Conclusion

- ✘ The AES on CPU is “easy” to disturb.
 - ✘ Powerful CPU that emit a lot of information.
 - ✘ AES software no protected
 - ✘ Easy to localize the EM emission (capacity to set up the FA)
- ✘ The crypto-accelerator is more difficult to disturb
 - ✘ Optimized /autonomous crypto-processor
 - ✘ AES hardware protected
 - ✘ Need to automatize the EM scan for side channel
 - ✘ More complex methodology to localize the EM emissions
 - ✘ Need Improvements on EM bench to automate the most as possible the injection EM parameters
- ✘ Complex systems require advanced methodology to succeed in fault injection on cryptographic implementation



Thank you

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